

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0199	0.03	1.4568
	Copper alloy	Iron (Fe)	7439-89-6	0.06632	0.1	4.856
	Copper alloy	Copper (Cu)	7440-50-8	66.23274	99.87	4,849.6872
Subtotal				66.31896	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.32747	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.97802	15.0	364.5
	Filler	Silica fused	60676-86-0	24.55823	74.0	1,798.2
	Flame retardant	Metal hydroxide		2.32308	7.0	170.1
Subtotal				33.1868	100	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.40971	100.0	30
Subtotal				0.40971	100	30
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.05531	100.0	4.05
Subtotal				0.05531	100	4.05
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01202	100.0	0.88
Subtotal				0.01202	100	0.88
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01119	65.0	0.819
	Lead alloy	Silver (Ag)	7440-22-4	0.0043	25.0	0.315
	Lead alloy	Antimony (Sb)	7440-36-0	0.00172	10.0	0.126
Subtotal				0.01721	100	1.26
Total				100.00001	100	NaN

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